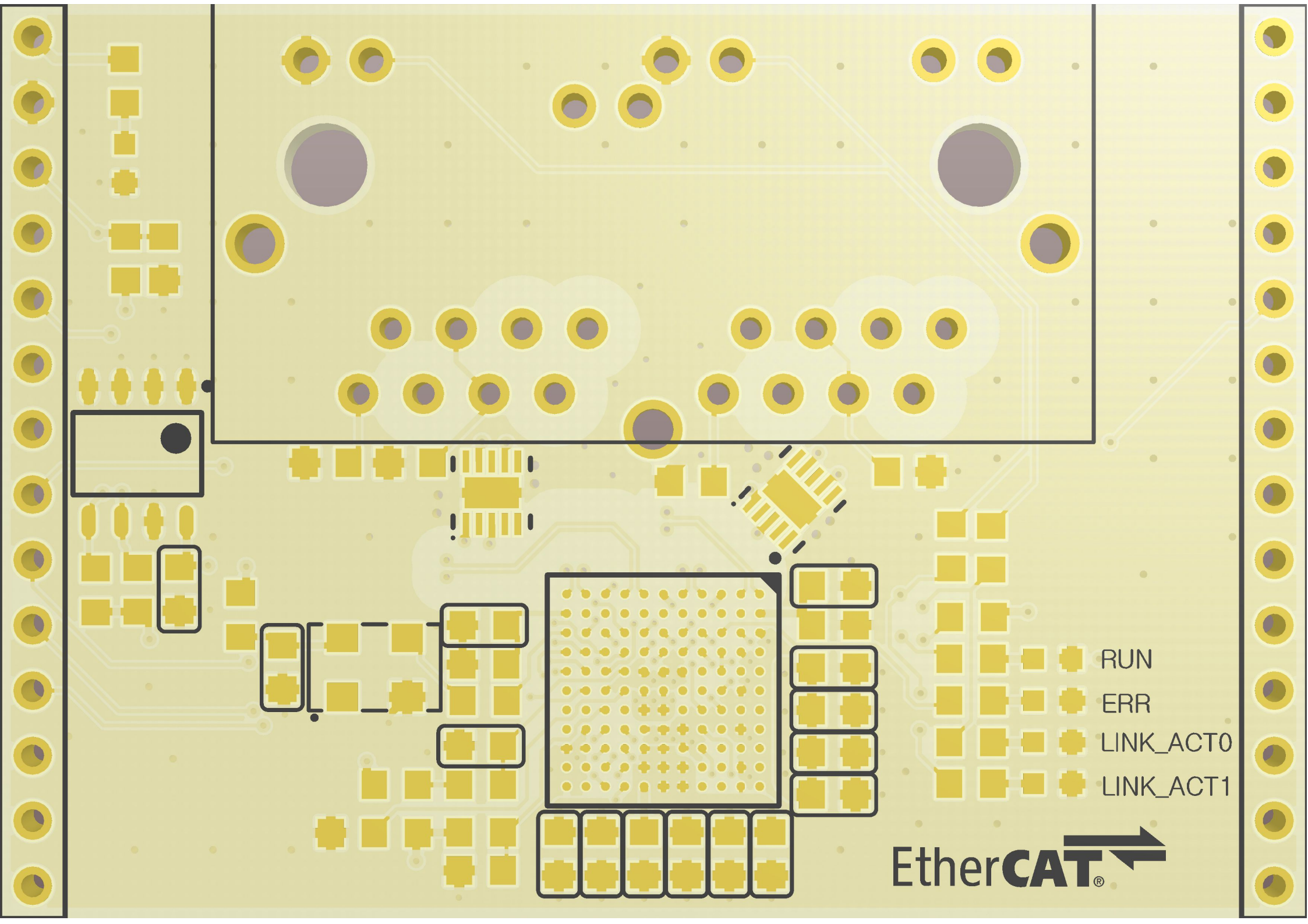


ASFLMB

- RUN
- ERR
- LINK\_ACT0
- LINK\_ACT1

EtherCAT<sup>®</sup>

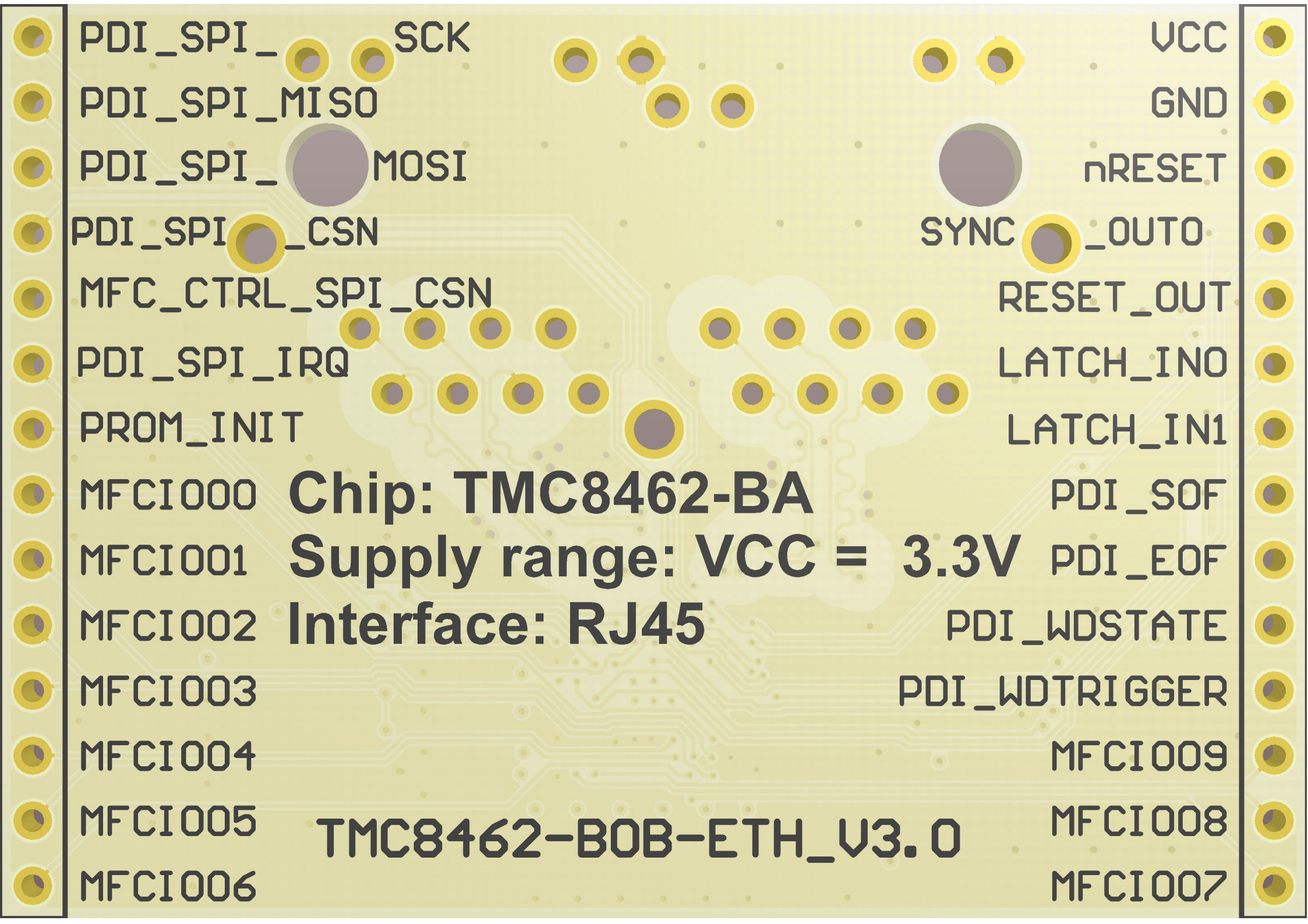




- RUN
- ERR
- LINK\_ACT0
- LINK\_ACT1

EtherCAT<sup>®</sup>





PDI\_SPI\_SCK

PDI\_SPI\_MISO

PDI\_SPI\_MOSI

PDI\_SPI\_CSN

MFC\_CTRL\_SPI\_CSN

PDI\_SPI\_IRQ

PROM\_INIT

MFCI000

MFCI001

MFCI002

MFCI003

MFCI004

MFCI005

MFCI006

Chip: TMC8462-BA

Supply range: VCC = 3.3V

Interface: RJ45

TMC8462-BOB-ETH\_V3.0

VCC

GND

nRESET

SYNC\_OUT

RESET\_OUT

LATCH\_IN0

LATCH\_IN1

PDI\_SOF

PDI\_EOF

PDI\_WDSTATE

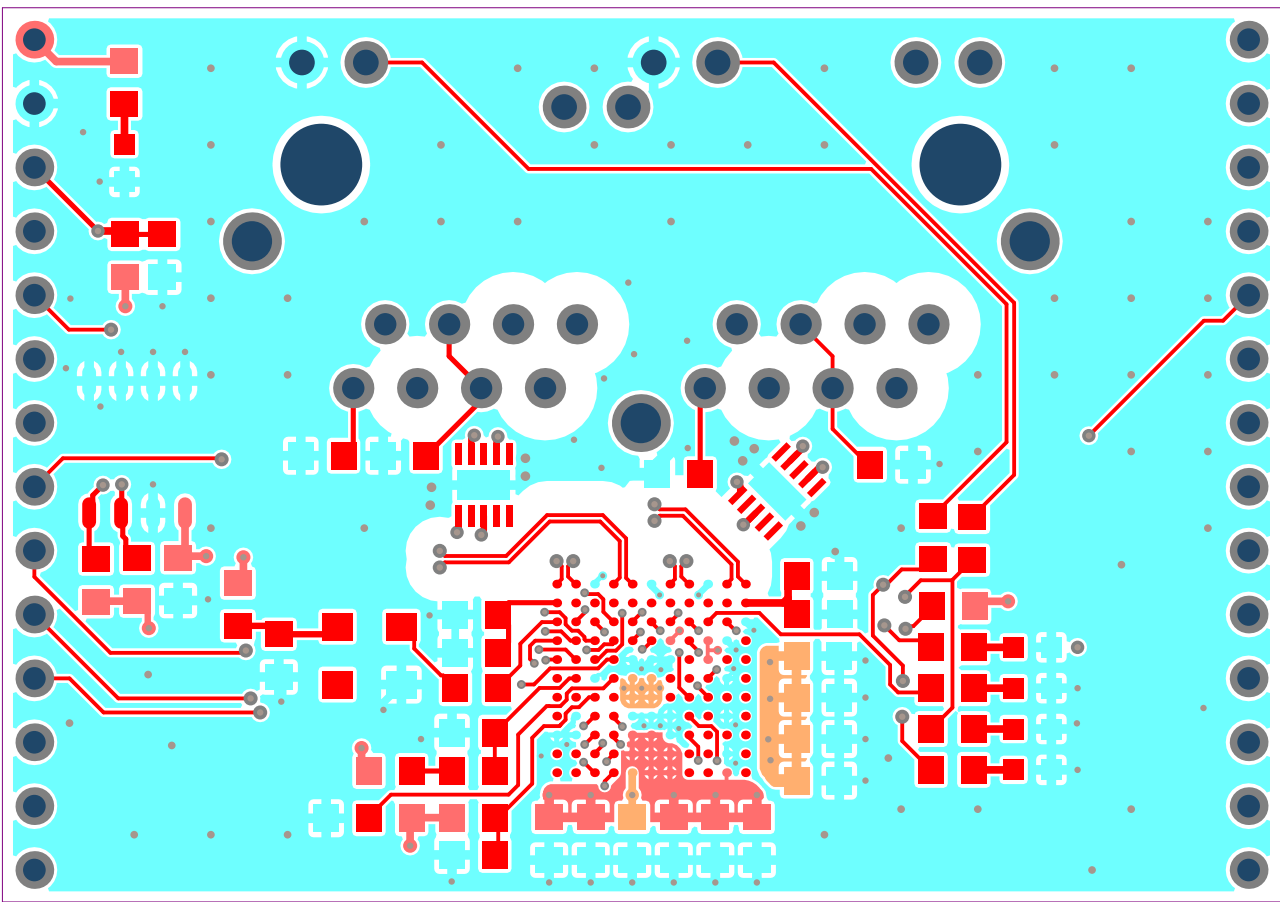
PDI\_WDTRIGGER

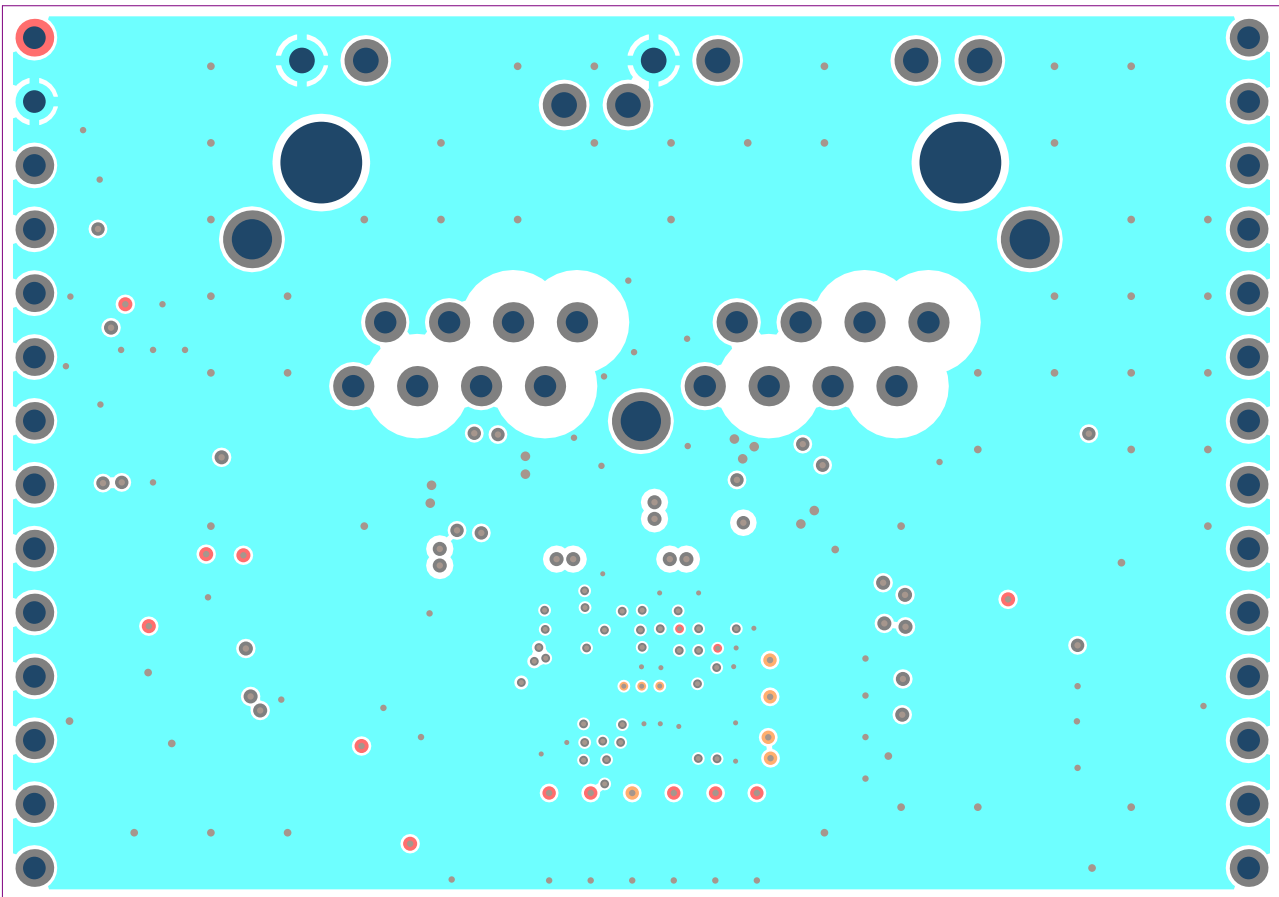
MFCI009

MFCI008

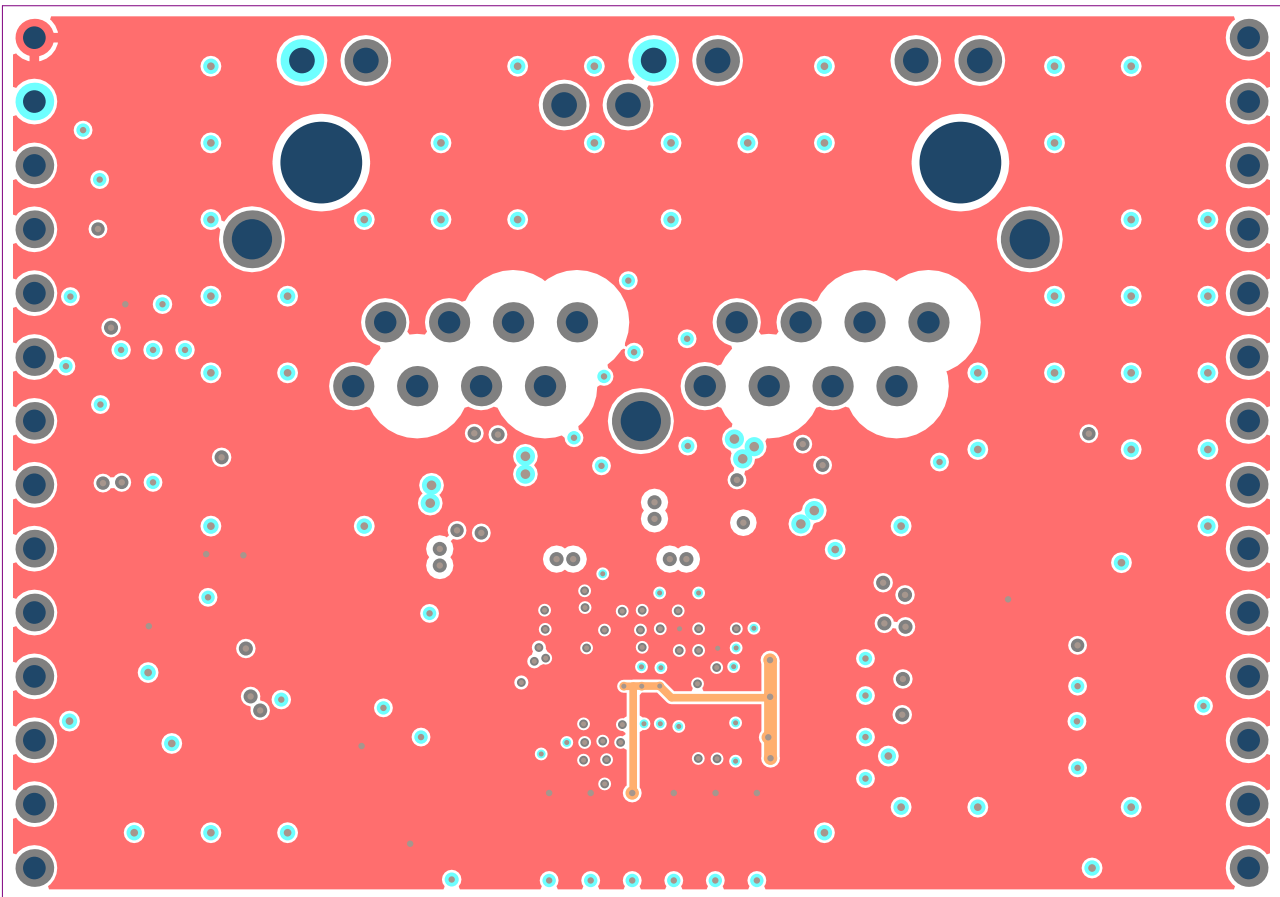
MFCI007

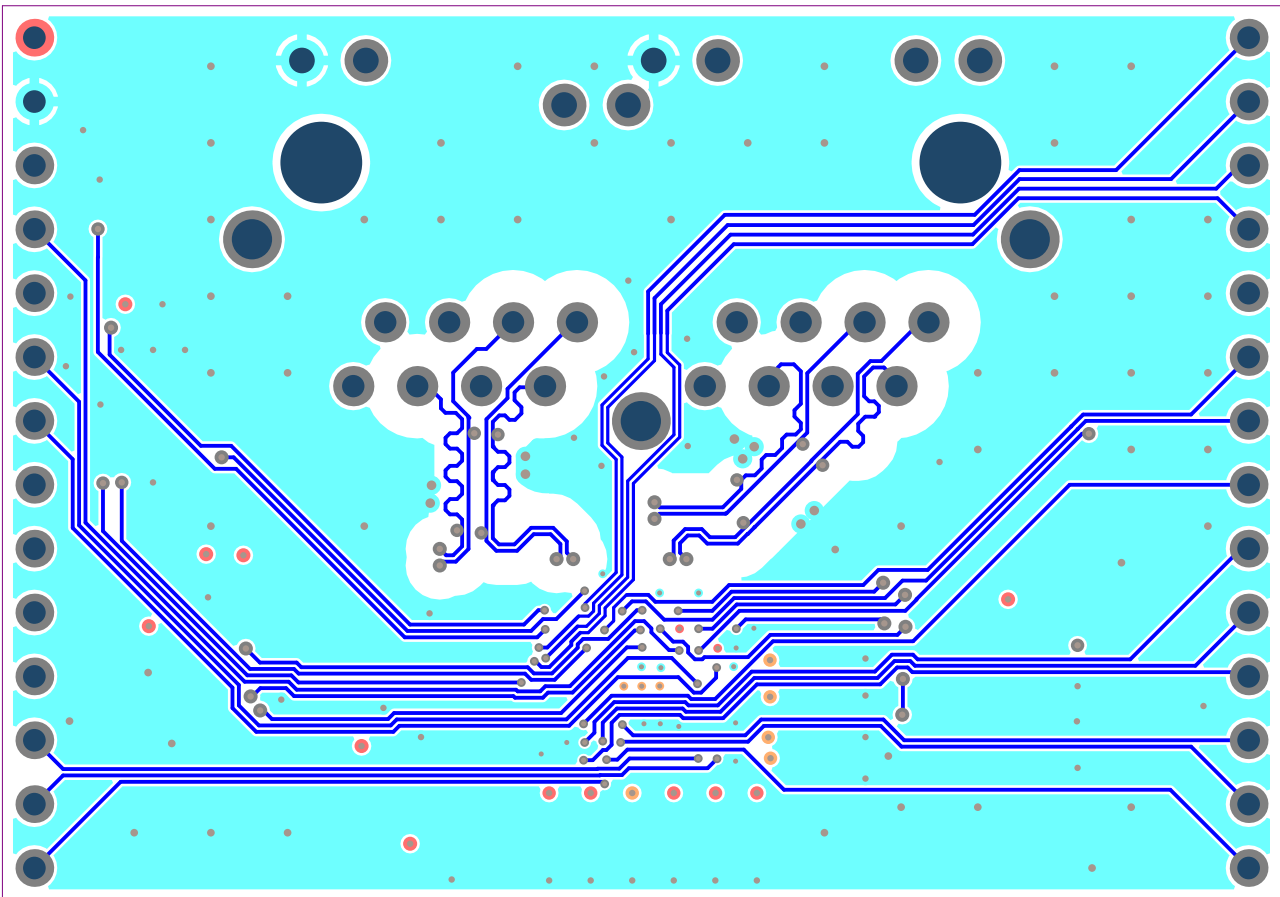




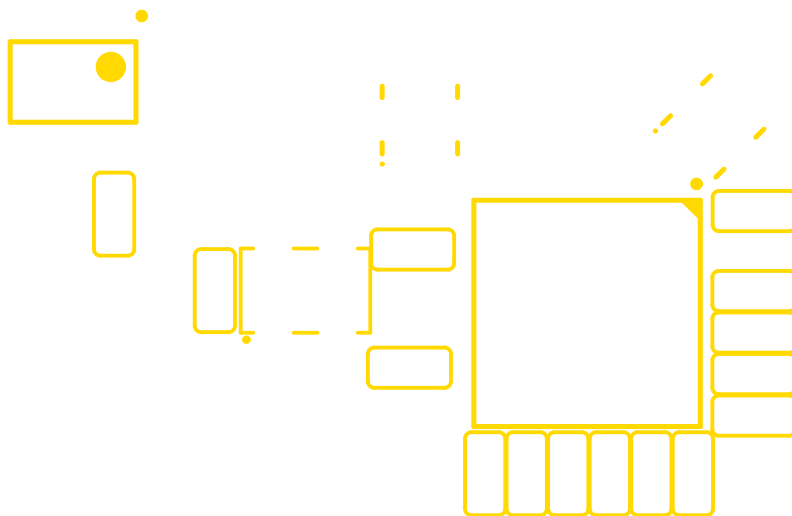








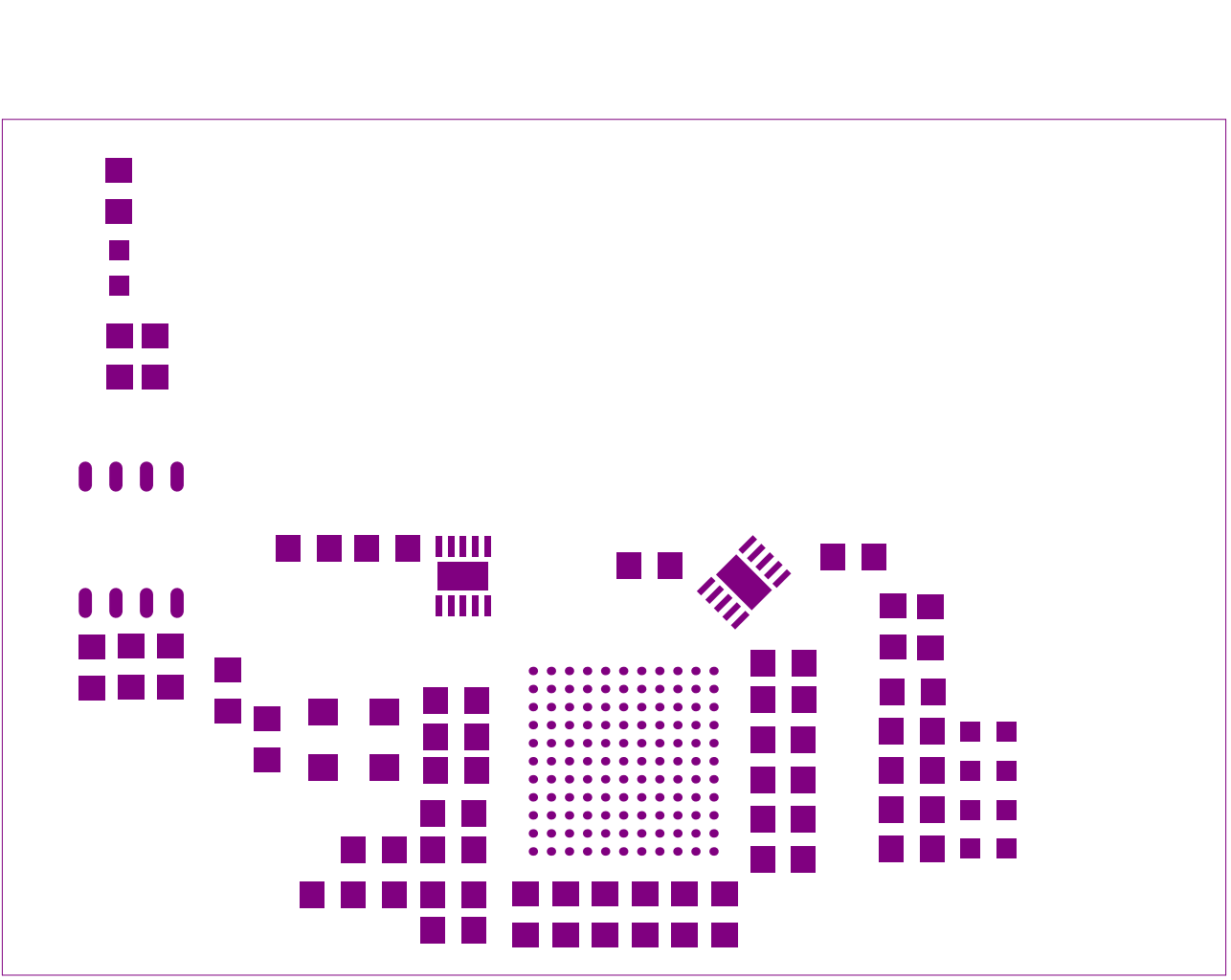




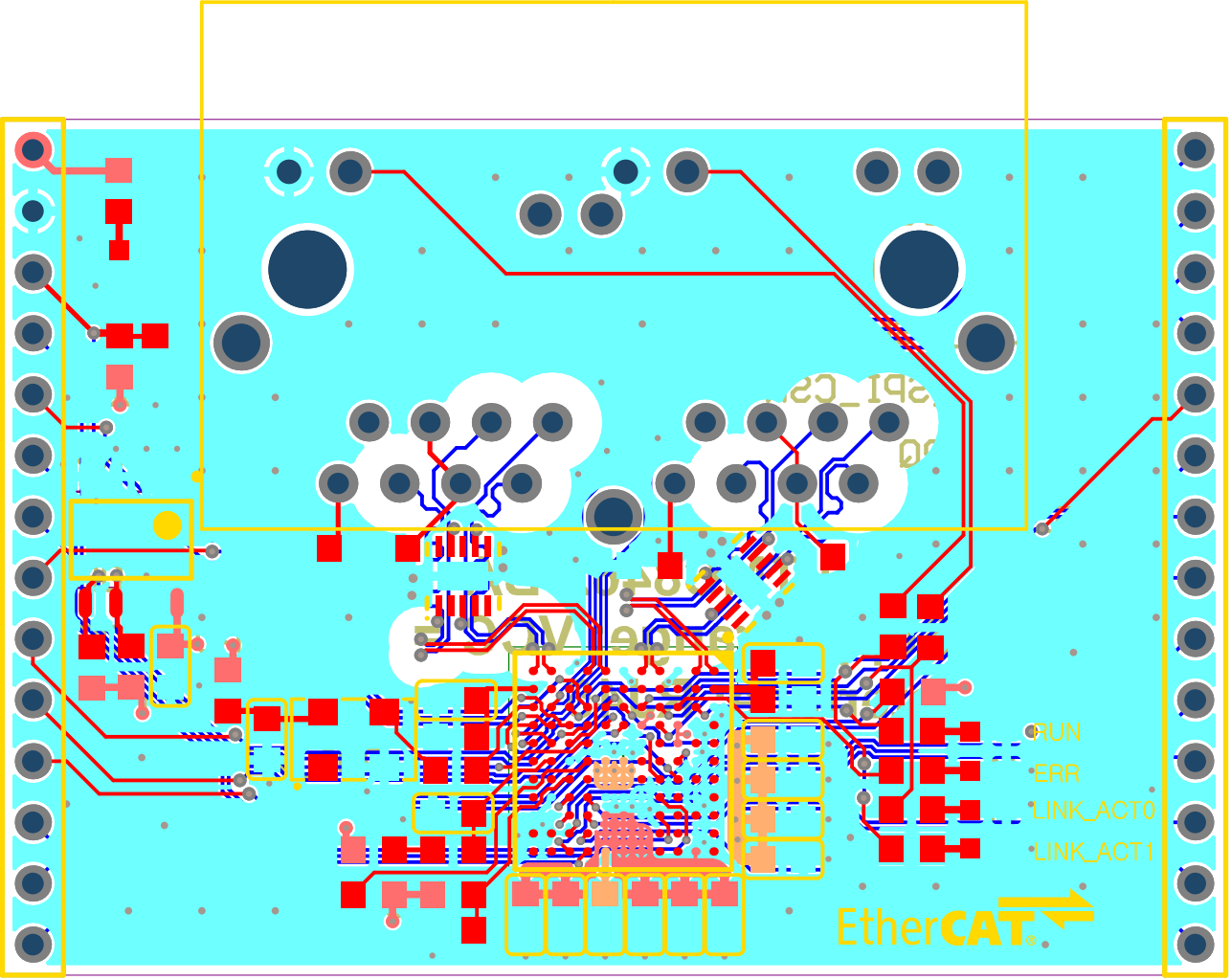
RUN  
ERR  
LINK\_ACT0  
LINK\_ACT1

PDI_SPI_	SCK	VCC
PDI_SPI_MISO		GND
PDI_SPI_	MOSI	nRESET
PDI_SPI_CS		SYNC_OUT0
MFC_CTRL_SPI_CS		RESET_OUT
PDI_SPI_IRQ		LATCH_IN0
PROM_INIT		LATCH_IN1
MFCI000	<b>Chip: TMC8462-BA</b>	PDI_SOF
MFCI001	<b>Supply range: VCC = 3.3V</b>	PDI_EOF
MFCI002	<b>Interface: RJ45</b>	PDI_WDSTATE
MFCI003		PDI_WDTRIGGER
MFCI004		MFCI009
MFCI005	<b>TMC8462-BOB-ETH_V3.0</b>	MFCI008
MFCI006		MFCI007

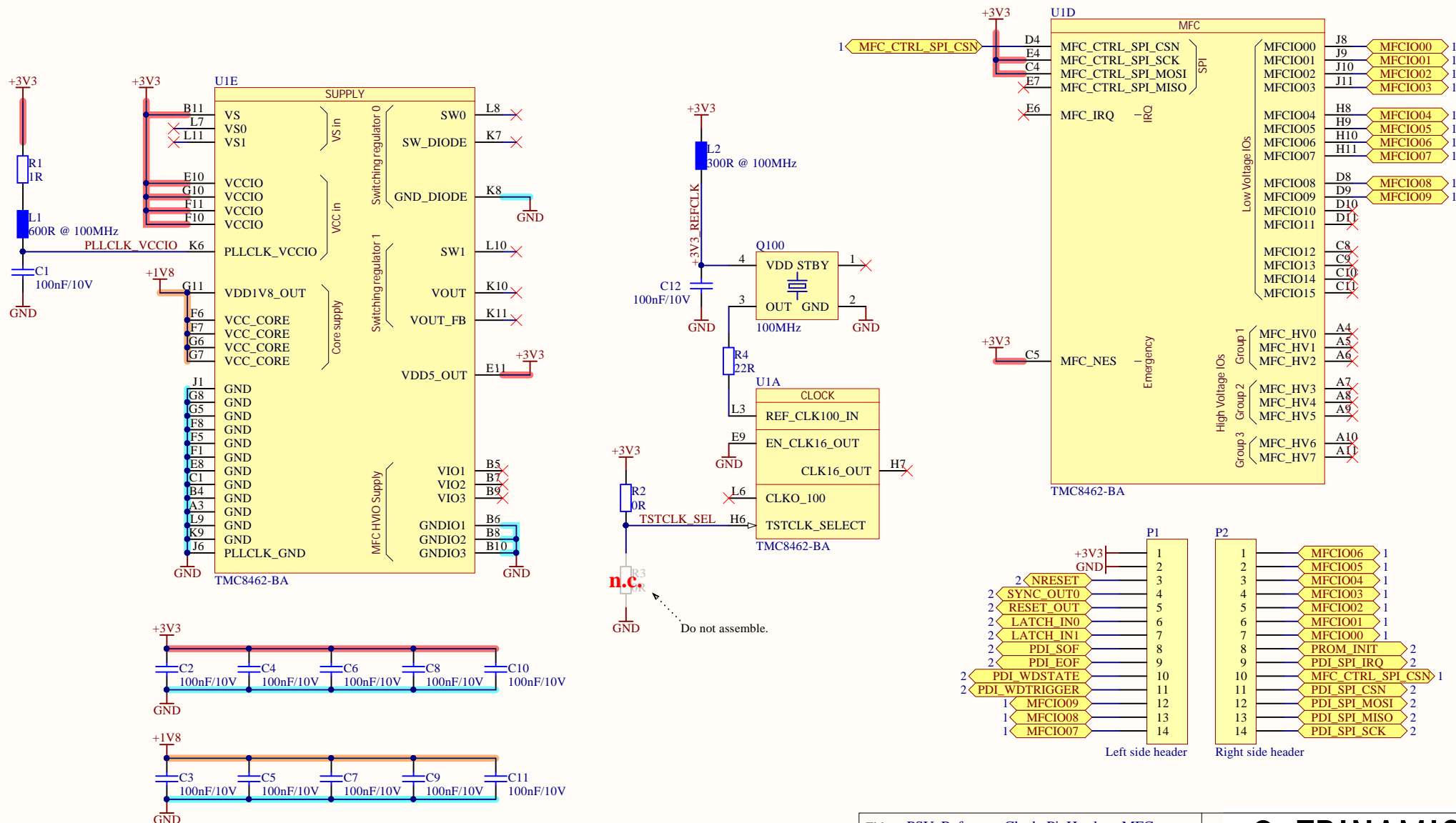








# PSU, Reference Clock, PinHeaders, MFC



Title: PSU, Reference Clock, PinHeaders, MFC

Size: A4 Project: TMC8462-BOB-ETH Version: 3.0

Date: 29.11.2017 Time: 16:45:21 Sheet 1 of 5

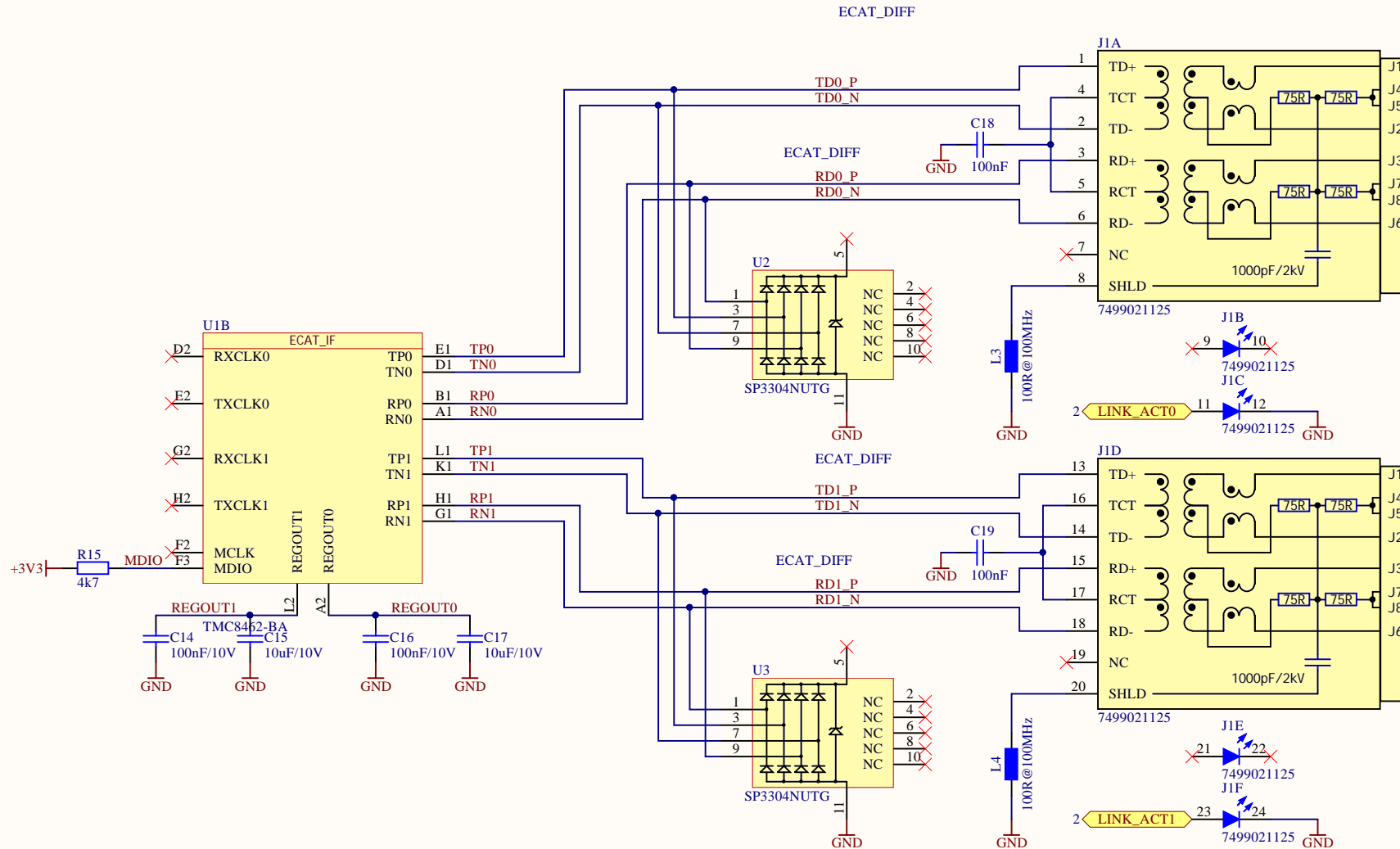
File: [1]\_PSU\_RefClock\_PinHeaders\_MFC.SchDoc







# EtherCAT, RJ45



Title: EtherCAT, RJ45		
Size: A4	Project: TMC8462-BOB-ETH	Version: 3.0
Date: 29.11.2017	Time: 16:45:22	Sheet 3 of 5
File: [3]_EtherCAT.SchDoc		



# ChangeLog

V1.0 - Initial design

V2.0 # 22.09.2017

- Fixed Q1 FOX924B pinout bug (swapped pin 3 & 4).

V3.0 # 24.11.2017

- Fixed bottom silkscreen typo (RJ54 -> RJ45)
- Removed SYNC\_OUT1 from header row. Connected RESET\_OUT instead. SYNC\_OUT1 remains unconnected
- Renamed the following pin names in the symbol:
  - o CLK\_IN\_EN\_100 renamed to TSTCLK\_SELECT
  - o CLKIO\_100 renamed to CLKO\_100
  - o REF\_CLK25\_IN renamed to REF\_CLK100\_IN
- Removed R2 and R3
- Connected pin H6 (new TSTCLK\_SELECT) directly to VCCIO (+3V3)
- Replaced Q1 with a 100MHz oscillator
- Modified NRESET connection: changed R7 to 10K and added a 10nF cap to GND.
- Added two additional green LEDs below the ERR and RUN led. One for LINK\_ACT0 and one for One for LINK\_ACT1.

# 27.11.2017

- Swapped RESET\_OUT and LATCH\_IN0 to have both LATCH\_INx pins next to each other.
- Added EtherCAT logo to top silkscreen.

# 28.11.2017

- Renamed FXSD0 to TXER0, FXSD1 to TXER1, FIB\_MOD0 to RXDV0, FIB\_MOD1 to RXDV1 and moved these signals to sub-part F where all the test signals are on the TMC8462 symbol.

# 29.11.2017

- Added the pull-up (VCCIO) and pull-down (GND) at pin TSTCLK\_SELECT.

Title: <a href="#">ChangeLog</a>		
Size: <a href="#">A4</a>	Project: <a href="#">TMC8462-BOB-ETH</a>	Version: <a href="#">3.0</a>
Date: <a href="#">29.11.2017</a>	Time: <a href="#">16:45:23</a>	Sheet <a href="#">4</a> of <a href="#">5</a>
File: <a href="#">ChangeLog.SchDoc</a>		



# TMC8462-BOB-ETH\_V3.0

U\_ChangeLog  
ChangeLog.SchDoc



U\_[1]\_PSU\_RefClock\_PinHeaders\_MFC  
[1]\_PSU\_RefClock\_PinHeaders\_MFC.SchDoc



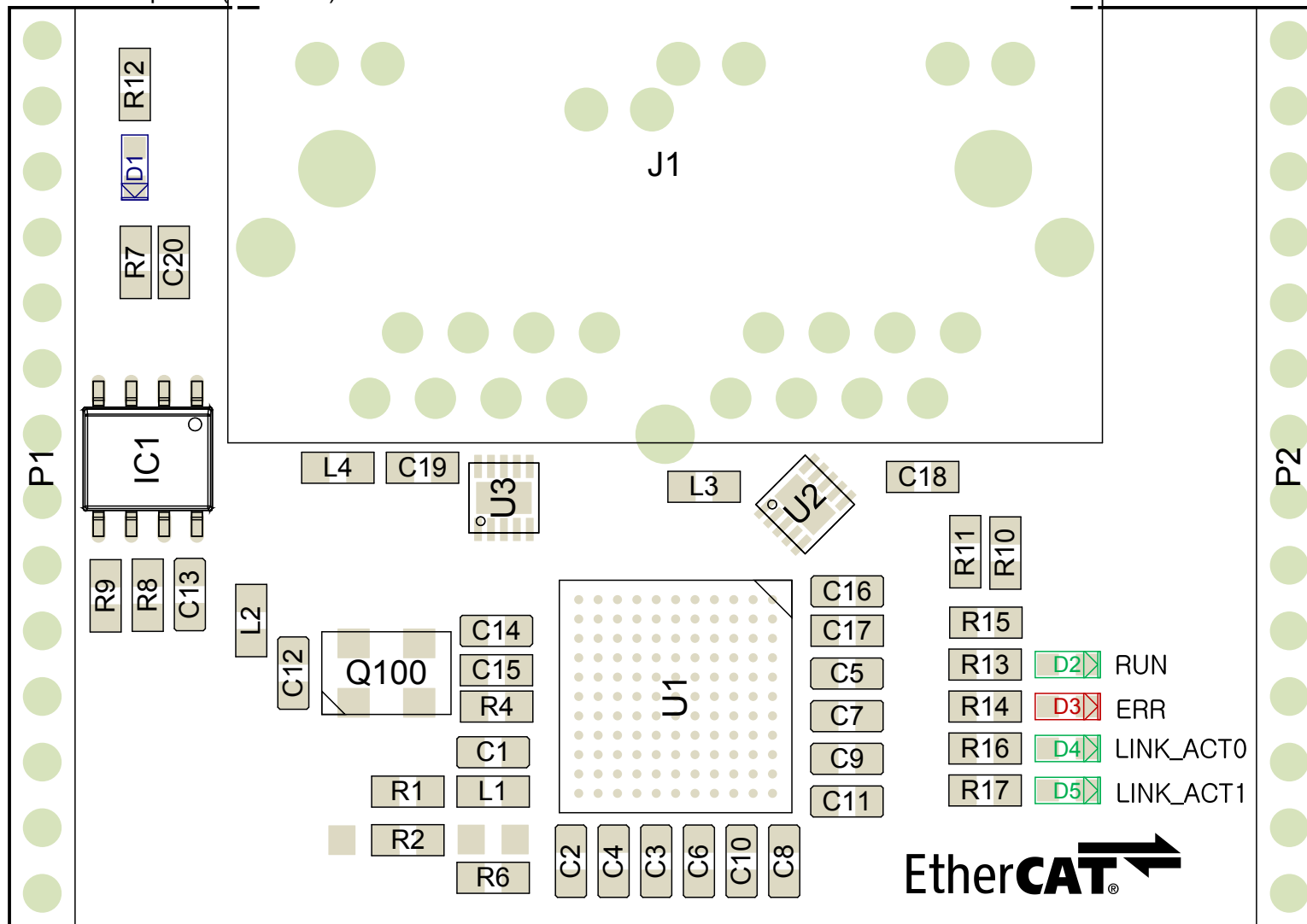
U\_[2]\_MCU\_EEPROM\_Indicators  
[2]\_MCU\_EEPROM\_Indicators.SchDoc



U\_[3]\_EtherCAT  
[3]\_EtherCAT.SchDoc



View from Top side (Scale 4:1)



Title: TMC8462-BOB-ETH

Version: 3.0

Date: 29.11.2017 Time: 16:45 16:45



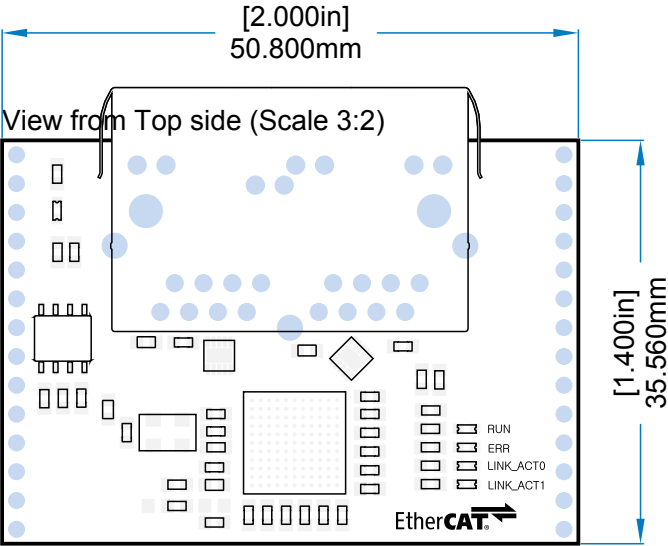
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Paste			Paste Mask	GTP
	Top Overlay			Legend	GTO
	Surface Material	0.010mm(0.400mil)	Solder Resist	Solder Mask	GTS
Copper	Top	0.018mm(0.689mil)		Signal	GTL
Core		0.254mm(10.000mil)	FR-4	Dielectric	
Copper	GND	0.035mm(1.378mil)		Signal	G1
Prepreg		1.000mm(39.370mil)	FR-4	Dielectric	
Copper	VM	0.035mm(1.378mil)		Signal	G2
Core		0.254mm(10.000mil)	FR-4	Dielectric	
Copper	Bottom	0.018mm(0.689mil)		Signal	GBL
Surface Material	Bottom Solder	0.010mm(0.400mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
	Bottom Paste			Paste Mask	GBP

Total thickness: 1.633mm(64.304mil)

Notes:

1. MATERIAL : FR-4-2 NATURAL EPOXY/FIBERGLASS
2. APPLY SOLDERMASK ON BOTH SIDES  
COLOR: WHITE  
FABRICATOR SHALL MAKE NECESSAY MODIFICATIONS TO SOLDERMASK PHOTOPLOT FILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
3. FINISH ALL EXPOSED COPPER SURFACES WITH IMMERSION GOLD.
4. HOLE SIZES APPLY AFTER PLATING.
5. APPLY SILKSCREEN TO BOTH SIDES  
COLOR: BLACK  
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PHOTOPLOT FILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
6. MODIFIED PHOTOPLOT FILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
7. ALL PRINTED CIRCUITBOARD NETS SHALL BE ELECTRICALLY TESTED FOR OPENS AND SHORTS.
8. FABRICATION OF PCB TO COMPLY WITH IPC-A-600 CLASS II . CURRENT REVISION.



Title: TMC8462-BOB-ETH

Version: 3.0

Date: 29.11.2017 Time: 16:45 16:45





# BOM

Project: TMC8462-BOB-ETH

Version: 3.0

Date: 29.11.2017

#	Quantity	MPN	Comment	Designator	Footprint	Description	Note	MF	
1	15	MC0603B104K100CT	100nF/10V	C1, C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C13, C14, C16	C0603_BYPASS	SMD Multilayer Ceramic Capacitor, 0603 [1608 Metric], 0.1 µF, 10 V, ± 10%, X7R, MC Series		Multicomp	
2	2	LMK107BBJ106MALT	10uF/10V	C15, C17	C0603	SMD Multilayer Ceramic Capacitor, 0603 [1608 Metric], 10 µF, 10 V, ± 20%, X5R, M Series		TAIYO YUDEN	
3	2	MC0603F104M500CT	100nF	C18, C19	C0603	Ceramic capacitor			
4	1	MC0603B103K500CT	10nF	C20	C0603	SMD Multilayer Ceramic Capacitor, 0603 [1608 Metric], 0.01 µF, 50 V, ± 10%, X7R, MC Series		MULTICOMP	
5	1	LTST-C191TBKT	LTST-C191TBKT	D1	LED_0603	Blue 470nm LED Indication - Discrete 3.3V 0603 (1608 Metric)		Lite-On	
6	3	LTST-C191KGKT	LTST-C191KGKT	D2, D4, D5	LED_0603	Green 571nm LED Indication - Discrete 2V 0603 (1608 Metric)		Lite-On	
7	1	LTST-C191KRKT	LTST-C191KRKT	D3	LED_0603	Red 631nm LED Indication - Discrete 2V 0603 (1608 Metric)		Lite-On	
8	1	24LC64-I/SN	24LC64-I/SN	IC1	SOIC127P600X175-8L	EEPROM, I2C, 64 Kbit, 8K x 8bit, 400 kHz, SOIC, 8 Pins		MICROCHIP	
9	1	7499021125	7499021125	J1	RJ45_7499021125	Modular Connector, RJ45, WE-RJ45 Series, Jack, 8 Contacts, 8 Ways, 2 Ports		WURTH ELEKTRONIK	
10	1	74279265	600R @ 100MHz	L1	L0603	Ferrite Bead, 600 ohm, 0603 [1608 Metric], 200 mA, 0.45 ohm, ± 25%		WURTH ELEKTRONIK	
11	1	742792641	300R @ 100MHz	L2	L0603	Ferrite Bead, 300 ohm, 0603 [1608 Metric], 2 A, 0.15 ohm, ± 25%		WURTH ELEKTRONIK	
12	2	MPZ1608S101A	100R@100MHz	L3, L4	L0603	Ferrite Bead, 100 ohm, 0603 [1608 Metric], MPZ Series, 3 A, 0.03 ohm, ± 25%		TDK	
13	1	ASFLMB-100.000MHZ-LR-T	100MHz	Q100	ASFLMB-100.000MHZ-LR-T	100MHz MEMS (Silicon) LVC MOS Oscillator 1.8 V ~ 3.3 V Standby (Pow er Down) 4-SMD, No Lead		Abracon LLC	
14	1	MCWR06W1R00FTL	1R	R1	R0603	SMD Chip Resistor, Thick Film, 1 ohm, 50 V, 0603 [1608 Metric], 100 mW, ± 1%, MCWR Series		MULTICOMP	
15	2	MCWR06X000 PTL	0R	R2, R6	R0603	SMD Chip Resistor, Thick Film, 0 ohm, 0603 [1608 Metric], 100 mW, MCWR Series		MULTICOMP	
16	1	MCWR06X22R0FTLV	22R / 100mW / 1%	R4	R0603	SMD Chip Resistor, Thick Film, 22 ohm, 50 V, 0603 [1608 Metric], 100 mW, ± 1%, MCWR Series		MULTICOMP	
17	1	MC0063W0603110K	10k	R7	R0603	SMD Chip Resistor, Thick Film, 10 kohm, 50 V, 0603 [1608 Metric], 63 mW, ± 1%, MC Series		MULTICOMP	
18	2	MC0063W060311K	1k	R8, R9	R0603	1 kohm, 50 V, 0603 [1608 Metric], 63 mW, ± 1%, MC Series		MULTICOMP	
19	7	MCWR06X1800FTL	180R	R10, R11, R12, R13, R14, R16, R17	R0603	SMD Chip Resistor, Thick Film, 180 ohm, 50 V, 0603 [1608 Metric], 100 mW, ± 1%, MCWR Series		MULTICOMP	
20	1	WR06X4701FTL	4k7	R15	R0603	SMD Chip Resistor, 4.7 kohm, 75 V, 0603 [1608 Metric], 100 mW, ± 1%, WR06 Series		WALSIN	
21	1	TMC8462-BA	TMC8462-BA	U1	BGA121C75P11X11_900X900X140	Integrated EtherCAT Slave Controller, GPIOs, SPI, I2C, PWM, STEP/DIR, 2x 100-Mbit Ethernet PHYs,		TRINAMIC	
22	2	SP3304NUTG	SP3304NUTG	U2, U3	SON50P260X55_HS-11N	TVS DIODE 3.3VWM 11.5VC UDFN10		Littelfuse Inc.	
Approved			Notes						52

